

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : Unassigned Confirmation No. Unassigned
Applicant : Joseph Bellaiche *et al.*
Filed : Concurrently
TC/A.U. : Unassigned
Examiner : Unassigned

Docket No. : FR 020116 US
Customer No. : 24738

Title: : Device Comprising Circuit Elements Connected by Bonding Bump
Structure

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

Sir:

Prior to calculation of the filing fee and examination please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims begin on page 3 of this paper.

Remarks/Arguments begin on page 6 of this paper.